

REMARKS

Claims 18-21 were withdrawn from consideration as the result of a restriction requirement.

Applicant thanks the Examiner for allowing claims 15-17 and for recognizing that claims 2 and 4-6 include allowable subject matter.

Claim 22 has been added.

Claims 1-17 and 22 are pending for further examination.

Claims 1, 3 and 7-14 were ejected as anticipated by JP 2001-352034 (Sakamoto et al.). Applicant respectfully requests reconsideration.

Claim 1, as amended, recites a circuit device that includes plating films formed on a surface of the die pad and on a surface of the bonding pad, respectively, wherein a second plating film *on the die pad* is spaced apart from a first plating film *on the die pad*. An example is illustrated in FIG. 1B in which the die pad is identified by 11, the first plating film is identified by 14A, and the second plating film is identified by 14B. A plating film 14C is on the surface of the bonding pad 12.

The Office action alleges that, in the JP 2001-352034, the film located just above the pad 51B (FIG. 9A) and to which the wire 55A is attached corresponds to the claimed second plating film. However, the film on top of the pad 51B in JP 2001-352034 corresponds to the plating film 14C on the *bonding* pad 12 in FIG. 1B of the pending specification. The film on the pad 51B in JP 2001-352034 is not on the pad 51A for the semiconductor chip 52A. Therefore, JP 2001-352034 does not disclose or suggest “a second plating film *on the die pad* [] spaced apart from a first plating film on the die pad” as recited in pending claim 1.

At least for that reason, the rejection of claim 1, as well as dependent claims 3 and 7-8, should be withdrawn.

Claim 9 recites a circuit device with a die pad on which a semiconductor element is mounted, a first bonding pad disposed in close vicinity to the die pad and electrically separated from the die pad, and a second bonding pad disposed in close vicinity to the die pad and formed integrally with the die pad. As shown in the example of FIG. 1A of the pending specification, the second bonding pad 12B is formed integrally (*i.e.*, as one piece) with the die pad 11, whereas the first bonding pad 12A is physically separate from the die pad.

In contrast, each of the bonding pads 51B in FIG. 9A of JP 2001-352034 is physically separate from the die pad 51A. Therefore, JP 2001-352034 does not disclose or suggest “a second bonding pad disposed in close vicinity to the die pad and formed integrally with the die pad, . . . wherein the second bonding pad is connected to the die pad through a wiring portion narrow in width” as recited in claim 9.

At least for that reason, the rejection of claim 9, as well as dependent claims 10-14,

It is believed that all of the pending claims have been addressed. However, the absence of a reply to a specific rejection, issue or comment does not signify agreement with or concession of that rejection, issue or comment. In addition, because the arguments made above may not be exhaustive, there may be reasons for patentability of any or all pending claims (or other claims) that have not been expressed. Finally, nothing in this paper should be construed as an intent to concede any issue with regard to any claim, except as specifically stated in this paper, and the amendment of any claim does not necessarily signify concession of unpatentability of the claim prior to its amendment.

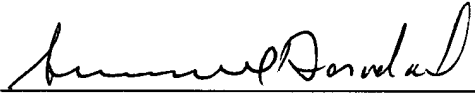
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Enclosed is a check for excess claim fees and a check for the petition of extension of time. Please apply any other charges or credits to deposit account 06-1050.

Respectfully submitted,

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